

Printed Circuit Board —by EAGLE

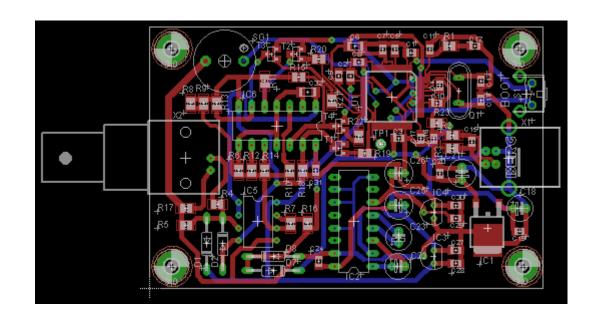
Outline

• 1.软件学习理念(EAGEL简介)

• 2.绘制流程

• 3.使用介绍

• 4.Key Points



1.Eagle 介绍

• A.免费开源

• B.国外使用很多(随之教材也会很多)例如: <u>sparkfun</u>

• C.绘制原理图(逻辑连线)和电路板(实物连线)

• 入门时间(参考): 2-3天

2.绘制流程

- •操作流程:
- •逻辑电路→绘制原理图→绘制实物图(*.board)→生成gerber文件
 - 纯软件使用(搭积木的过程)————

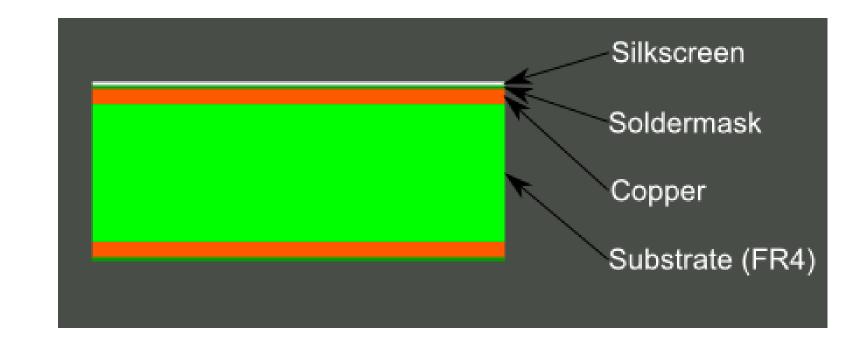
- 目的:
- •实现目标 > 完成逻辑连线 > 完成实物连线 > 转化成工厂加工文件

3.使用介绍

- 0."层"
- 1.界面
- 2.操作
 - a.添加元器件(绘制)
 - b.连线
 - c.布线
 - d.敷铜(<u>教程</u>)

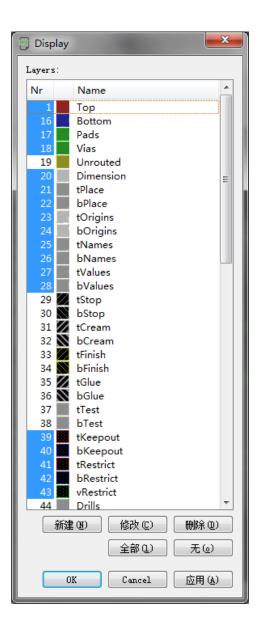
3.0 "层"

- 0.对称的
- 丝网层
- 组焊层
- 铜层
- 衬底层

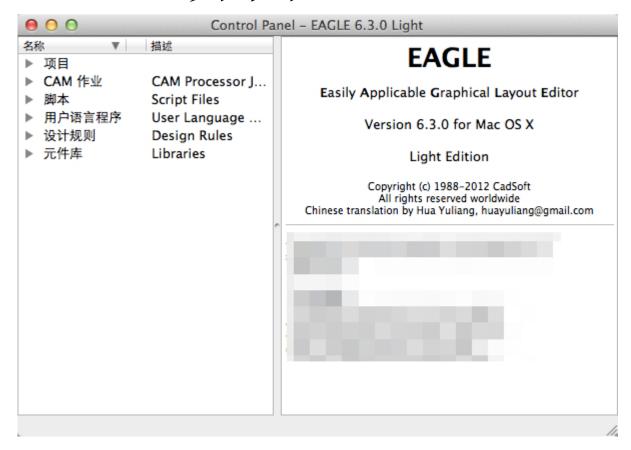


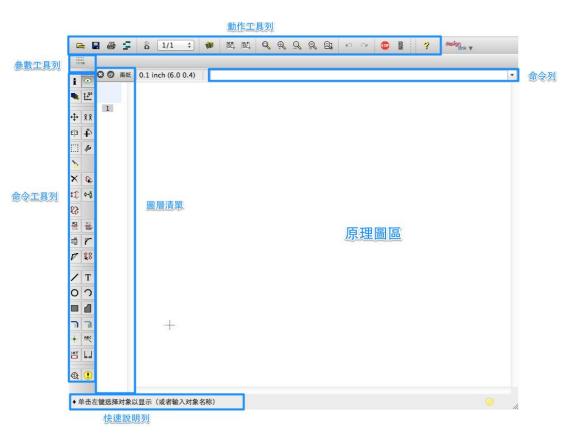
3.0 "层"

	Color	Layer Namo	Layer	Layer Purpose	
		Тор	1	Top layer of copper	
		Bottom	16	Bottom layer of copper	
		Pads	17	I nrough-hole pads. Any part of the green circle is exposed copper on <i>both</i> top and bottom sides of the board.	
		Vias	18	Vias. Smaller copper-filled drill holes used to route a signal from top to bottom side. These are usually covered over by soldermask. Also indicates copper on both layers.	
		Unrouted	19	Airwires. Rubber-band-like lines that show which pads need to be connected.	
		Dimension	20	Outline of the board.	
		tPlace	21	Silkscreen printed on the top side of the board.	
		bPlace	22	Silkscreen printed on the bottom side of the board.	Ш
		tOrigins	23	Top origins, which you click to move and manipulate an individual part.	
		bOrigins	24	Origins for parts on the bottom side of the board.	
	// Hatch	tStop	29	Top stopmask. These define where soldermask should <i>not</i> be applied.	
	\\ Hatch	bStop	30	Absent soldermask on the bottom side of the board.	
		Holes	45	Non-conducting (not a via or pad) holes. These are usually drill holes for stand-offs or for special part requirements.	
		tDocu	51	Top documentation layer. Just for reference. This might show the outline of a part, or other useful information.	



3.1 界面





3.2 操作

(空白)

4. Key Points

- 元器件的添加
 - 库(一般都能找到)
 - 自己绘制

- •尺寸设置
 - 网格大小设置

- 快捷键
 - 会让你感觉人生很美好

THANKS

(完)